



Material Content Data Sheet



Sales Product Name		TLE5041PLUSC		Issued		28. August 2013		
MA#		MA001038636						
Package		PG-SSO-2-53		Weight*		169.34 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.257	0.74	0.74	7421	7421
leadframe	non noble metal	chromium	7440-47-3	0.288	0.17		1703	
	non noble metal	titanium	7440-32-6	0.288	0.17		1703	
	noble metal	silver	7440-22-4	0.384	0.23		2270	
	non noble metal	tin	7440-31-5	0.577	0.34		3405	
	non noble metal	copper	7440-50-8	94.576	55.84	56.75	558496	567577
wire	noble metal	gold	7440-57-5	0.044	0.03	0.03	259	259
encapsulation	organic material	carbon black	1333-86-4	0.579	0.34		3422	
	plastics	epoxy resin	-	10.429	6.16		61588	
	inorganic material	silicondioxide	60676-86-0	46.932	27.71	34.21	277145	342155
leadfinish	non noble metal	tin	7440-31-5	6.247	3.69	3.69	36890	36890
plating	noble metal	silver	7440-22-4	1.029	0.61	0.61	6077	6077
glue	plastics	epoxy resin	-	0.102	0.06		602	
	noble metal	silver	7440-22-4	0.407	0.24	0.30	2406	3008
smd	inorganic material	leadoxide	1317-36-8	0.001	0.00		7	
	inorganic material	titandioxide	13463-67-7	0.148	0.09		874	
	inorganic material	leadtitanate	12060-00-3	0.031	0.02		183	
	plastics	epoxy resin	-	0.002	0.00		12	
	inorganic material	bismuth trioxide	1304-76-3	0.255	0.15		1506	
	noble metal	palladium	7440-05-3	0.474	0.28		2800	
	noble metal	silver	7440-22-4	1.499	0.89		8852	
	inorganic material	bariumtitanate	12047-27-7	3.790	2.24	3.67	22379	36613
*deviation	< 10%					Sum in total:	100,00	1000000

Important Remarks:

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